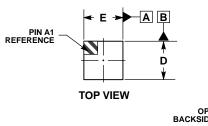
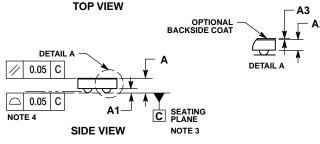
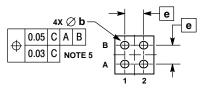


WLCSP4, 0.84x0.86 CASE 567DC ISSUE F

DATE 14 Jul 2016

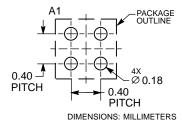






BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- r 14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.

- COPLANARITY APPLIES TO SPHERICAL CROWNS
 OF THE CONTACT BALLS.
 DIMENSION b IS MEASURED AT THE MAXIMUM
 CONTACT BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α			0.38
A1	0.08	0.10	0.12
A2	0.23 REF		
A3	(0.025 REI	=
b	0.16	0.18	0.20
D	0.82	0.84	0.86
E	0.84	0.86	0.88
е		0.40 BSC	;

GENERIC MARKING DIAGRAM*



= Specific Device Code

Υ = Year

= Date Code M

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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NEW STANDARD:		"CONTROLLED
DESCRIPTION:	WLCSP4, 0.84X0.86	_

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98AON56821	E

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ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY V. CRACIUNOIU.	03 MAY 2011
Α	CHANGED DIMENSIONS D AND E TO 0.866 X 0.842. REQ. BY V. CRACIUNOIU.	04 AUG 2011
В	CHANGED DIMENSIONS D AND E TO 0.86 X 0.84. CHANGED DIMENSIONS A, A1 AND A2. REQ. BY V. CRACIUNOIU.	18 JUN 2012
С	REVERSED DIMENSION D AND E LABELS TO 0.84 X 0.86. REQ. BY V. CRACIUN-OIU.	28 NOV 2012
D	ADDED DETAIL A AND A3 DIMENSION FOR OPTIONAL DIE COAT REQ. BY V. CRACIUNOIU.	19 DEC 2012
E	MODIFIED TOLERANCES IN TOP AND SIDE VIEWS. REQ. BY A. SARWARI.	19 JAN 2016
F	CORRECTED DETAIL A, CHANGED TOLERANCES AND ADDED NOMINAL VALUES. REQ. BY V. CRACIUNOIU.	14 JUL 2016

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